

General

- Chip size 2512
- Resistance value from 0.5mΩ to 50mΩ
- High power rating
- Low inductance 0.5nH to 5nH
- Low TCR
- Compatible with RoHS & Halogen free

Application

- Switching model power supply
- Battery pack
- Notebook, personal computer
- Test Instrument
- Power Amplifier

Electrical Specifications

| Type | Power Rating at 70°C(W) | Electrode (mm) | Resistance Range (mΩ) | TCR (ppm/°C) | Resistance Tolerance | Operation Temp. Range |
|------|-------------------------|----------------|-----------------------|--------------|----------------------|-----------------------|
| 2512 | 2、 3 | 1.90±0.25 | 0.5 | ±160 | ±1%(F) | -55°C~+170°C |
| | | 0.90±0.30 | 1 | ±100 | ±0.5%(D) ±1%(F) | |
| | | 0.90±0.30 | 1.5 | ±100 | ±1%(F) | |
| | | 0.90±0.30 | 2~50 | ±50 | ±0.5%(D) ±1%(F) | |

Part Number Information

SMA 25 A 2 F R001 T
【1】 **【2】** **【3】** **【4】** **【5】** **【6】** **【7】**

【1】 Series Name: Sart Metal Strip Type

【2】 Chip size: 25: 2512

【3】 Material Code: A:Alloy

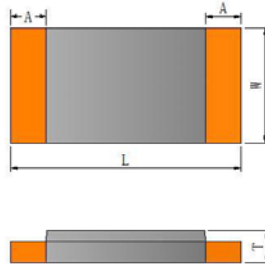
【4】 Power Code: 2: 2W; 3: 3W

【5】 Resistance Tolerance: F: ±1%

【6】 Resistance Code: R001 = 1 mΩ ; 0M50 = 0.5 mΩ

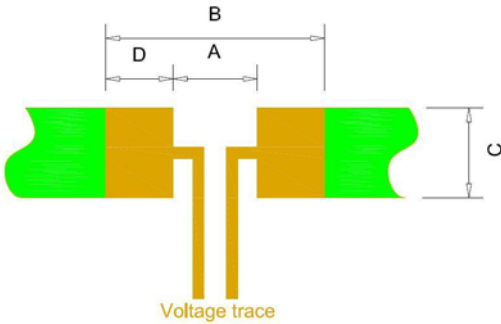
【7】 Packaging Code: T:Tape& Reel B: Bulk Pack

Dimensions



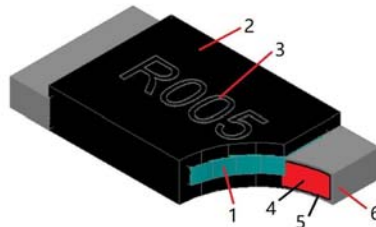
| Type | Power Rating at 70°C(W) | Resistance Range (mΩ) | L (mm) | W (mm) | T (mm) | A (mm) |
|------|-------------------------|-----------------------|-----------|-----------|-----------|-----------|
| 2512 | 2、3 | 0.5 | 6.40±0.30 | 3.20±0.30 | 1.05±0.20 | 1.90±0.25 |
| | | 1~4 | 6.40±0.30 | 3.20±0.30 | 1.10±0.20 | 0.90±0.30 |
| | | 5~50 | 6.40±0.30 | 3.20±0.30 | 0.90±0.20 | 0.90±0.30 |

Recommended Land Patterns



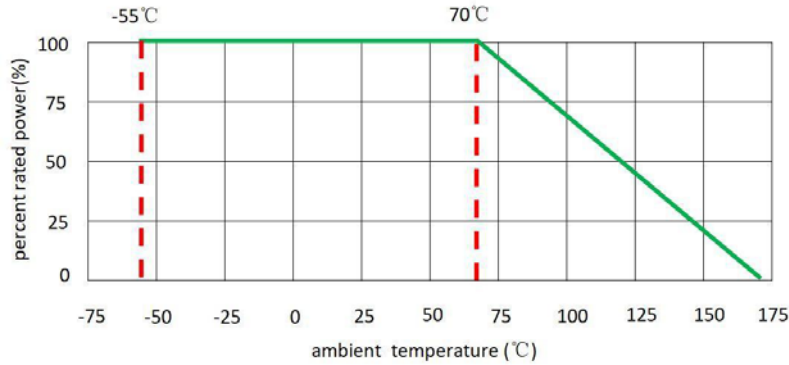
| Type | Resistance Range (mΩ) | A (mm) | B (mm) | C (mm) | D (mm) |
|------|-----------------------|--------|--------|--------|--------|
| 2512 | 0.5 | 1.50 | 7.40 | 3.57 | 2.95 |
| | 1~50 | 3.18 | 7.40 | 3.57 | 2.11 |

Materials



| No. | Materials | No. | Materials |
|-----|-------------------------|-----|-----------|
| 1 | Alloy | 4 | Copper |
| 2 | Epoxy molding compounds | 5 | Nickel |
| 3 | Marking | 6 | Tin |

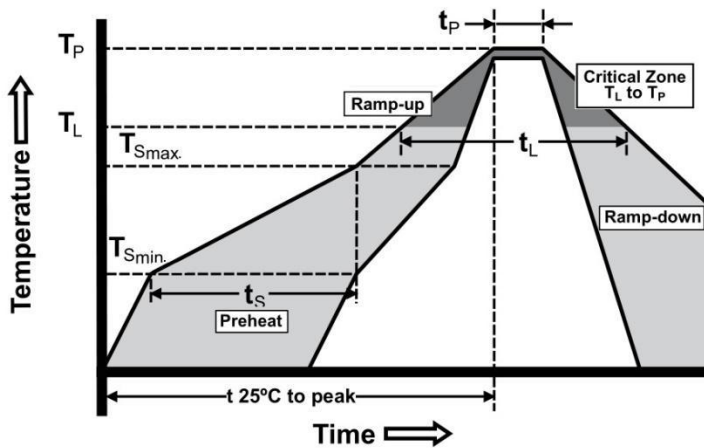
Power Derating Curve



Recommended Solder Curve

1. Infrared Reflow

- Temperature: 260°C
- Time: 5sec Max.
- Recommend Reflow profile:



| Profile Feature | Pb-Free Assembly |
|--|------------------|
| Average Ramp-up Rate (Tsmax to Tp) | 3°C/sec Max. |
| Preheat Temperature Min.(Tsmin) | 150°C |
| Preheat Temperature Max.(Tsmax) | 200°C |
| Preheat Time(Tsmin to Tsmax) | 60sec~120sec |
| Peak Temperature(Tp) | 260°C |
| Time within 5°C of actual Peak Temperature(Tp) | 5sec |
| Melting tin time(TL) | 20sec~30sec |
| Ramp-down Rate | 6°C/sec Max. |
| Time 25°C to peak Temperature | 8 min Max. |

2. Wave soldering

- Reservoir Temperature: 260°C
- Time in Reservoir: 10sec Max.

3. Hand Soldering

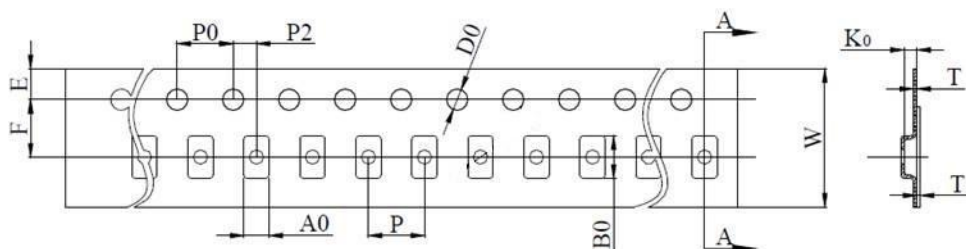
- Temperature: 350°C
- Time: 5sec Max.

Product Characteristics

| Item | Test condition / Methods | Performance | Standard |
|---|---|---|--------------------|
| Short Time Overload | $P = 5P_r$; $T = 25^{\circ}\text{C} \pm 2^{\circ}\text{C}$, $t = 5\text{sec}$ | $ \Delta R \leq \pm(1\% + 0.5\text{ m}\Omega)$ | IEC 60115-1 4.13 |
| Temperature Coefficient of Resistance (TCR) | $\text{TCR} = (R - R_0) / R_0 (T_2 - T_1) \times 10^6$ Test temperature: $+25^{\circ}\text{C} \sim +125^{\circ}\text{C}$ | Refer to SART Spec | IEC 60115-1 4.8 |
| Thermal Shock | $-55^{\circ}\text{C} (30\text{min}) / +150^{\circ}\text{C} (30\text{ min})$, 100 cycles | $ \Delta R \leq \pm(1\% + 0.5\text{ m}\Omega)$ | IEC 60115-1 4.19 |
| Resistance to Solder Heat | $265^{\circ}\text{C} \pm 5^{\circ}\text{C}$, $20\text{sec} \pm 1\text{sec}$ | $ \Delta R \leq \pm(1\% + 0.5\text{ m}\Omega)$ | IEC 60115-1 4.18 |
| Solderability | $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$, $3\text{sec} \pm 0.5\text{sec}$ | 95% coverage Min. | IEC 60115-1 4.17 |
| Load Life | 1000 hours at rated power, $70^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 1.5hours "ON", 0.5hours "OFF" | $ \Delta R \leq \pm(2\% + 0.5\text{ m}\Omega)$ | IEC 60115-1 4.25.1 |
| Moisture Load Life (60°C、95%RH) | $T = 60^{\circ}\text{C} \pm 2^{\circ}\text{C}$; $\text{RH} = 95\%$; $V_{\text{test}} = V_{\text{max}}$; $t = 1.5\text{hours "ON", 0.5hours "OFF", 1000hours}$ | $ \Delta R \leq \pm(2\% + 0.5\text{ m}\Omega)$ | IEC 60115-1 4.24 |
| Bending test | Bending width 2mm, Epoxy thickness 1.6mm, Fulcrums distance 90mm | $ \Delta R \leq \pm(1\% + 0.5\text{ m}\Omega)$ | IEC 60115-1 4.33 |
| High Temp. Exposure | $T = +170^{\circ}\text{C} \pm 2^{\circ}\text{C}$; $t = 1000\text{hours}$ | $ \Delta R \leq \pm(1\% + 0.5\text{ m}\Omega)$ | IEC60115-1 4.25 |
| Low Temp. Storage | $T = -55^{\circ}\text{C} \pm 2^{\circ}\text{C}$; $t = 1000\text{hours}$ | $ \Delta R \leq \pm(1\% + 0.5\text{ m}\Omega)$ | IEC60115-1 4.25 |
| Mechanical Shock | $a = 100\text{G}$, $t = 11\text{ms}$, 5 times shock | $ \Delta R \leq \pm(1\% + 0.5\text{ m}\Omega)$ | IEC60115-1 4.21 |

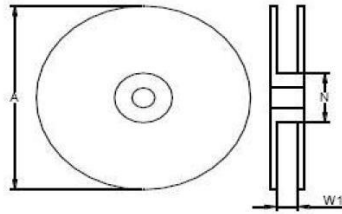
Packaging

1. Tape Packaging Dimensions



| Type | Power (w) | Resistance (mΩ) | A0 (mm) | B0 (mm) | W (mm) | F (mm) | E (mm) | T (mm) |
|------|-----------|-----------------|-----------|-----------|------------|-----------|-----------|---------------------------------------|
| 2512 | 2 | 0.5~4 | 3.40±0.20 | 6.75±0.20 | 12.00±0.30 | 5.50±0.10 | 1.75±0.10 | 0.20±0.10 |
| | | 5~50 | 3.40±0.20 | 6.75±0.20 | 12.00±0.30 | 5.50±0.10 | 1.75±0.10 | 0.20±0.10 |
| | 3 | 0.5~50 | 3.40±0.20 | 6.75±0.20 | 12.00±0.30 | 5.50±0.10 | 1.75±0.10 | 0.20±0.10 |
| Type | Power (w) | Resistance (mΩ) | P (mm) | P0 (mm) | P2 (mm) | D0 (mm) | T1 (mm) | K0 (mm) |
| 2512 | 2 | 0.5~4 | 4.00±0.10 | 4.00±0.10 | 2.00±0.10 | 1.55±0.10 | Max. 0.10 | 1.3 ^{+0.20} _{-0.10} |
| | | 5~50 | 4.00±0.10 | 4.00±0.10 | 2.00±0.10 | 1.55±0.10 | Max. 0.10 | 1.00±0.20 |
| | 3 | 0.5~50 | 4.00±0.10 | 4.00±0.10 | 2.00±0.10 | 1.55±0.10 | Max. 0.10 | 1.3 ^{+0.20} _{-0.10} |

2. Reel Dimensions

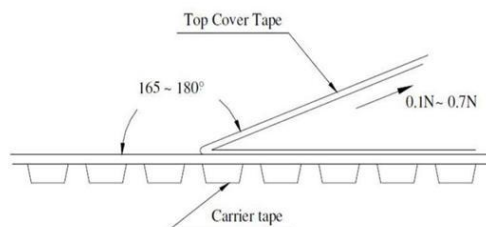


| Type | A (mm) | N (mm) | W1 (mm) |
|------|-------------|------------|------------|
| 2512 | 178.00±5.00 | 60.00±2.00 | 13.00±1.00 |

3. Quantity of Package

| Type | Power (w) | Resistance Range(mΩ) | Quantity(pcs) |
|------|-----------|----------------------|---------------|
| 2512 | 2 | 0.5~4 | 3000 |
| | | 5~50 | 4000 |
| | 3 | 0.5~50 | 3000 |

4. Peeling Test



Storage

- The ambient temperature shall between 5°C~30°C.
- The relative humidity recommended for storage is between 25%RH~60%RH.
- Sealed plastic bags with desiccant shall be used to reduce the oxidation of the termination and shall only be opened prior to use.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.